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74LVC377

Octal D-type flip-flop with data enable; positive-edge trigger

Rev. 6 — 20 November 2012 Product data sheet

1. General description

The 74LVC377 has eight edge-triggered D-type flip-flops with individual inputs (D) and outputs (Q). A common clock input (CP) loads all flip-flops simultaneously when data enable input ($\overline{E}$) is LOW. The state of each D input, one set-up time before the LOW to HIGH clock transition, is transferred to the corresponding output (Qn) of the flip-flop. Input $\overline{E}$ must be stable only one set-up time prior to the LOW to HIGH transition for predictable operation.

2. Features and benefits

- Wide supply voltage range from 1.2 V to 3.6 V
- Inputs accept voltages up to 5.5 V
- CMOS low power consumption
- Direct interface with TTL levels
- Output drive capability 50 Ω transmission lines at 125 °C
- Complies with JEDEC standard:
  - JESD8-7A (1.65 V to 1.95 V)
  - JESD8-5A (2.3 V to 2.7 V)
  - JESD8-C/JESD36 (2.7 V to 3.6 V)
- ESD protection:
  - HBM JESD22-A114F exceeds 2000 V
  - MM JESD22-A115-B exceeds 200 V
  - CDM JESD22-C101E exceeds 1000 V
- Specified from −40 °C to +85 °C and from −40 °C to +125 °C

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74LVC377D	−40 °C to +125 °C	SO20	plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
74LVC377DB	−40 °C to +125 °C	SSOP20	plastic shrink small outline package; 20 leads; body width 5.3 mm	SOT339-1
74LVC377PW	−40 °C to +125 °C	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1

4. Functional diagram

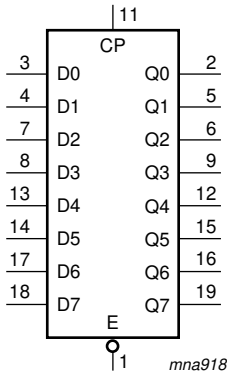


Fig 1. Logic symbol

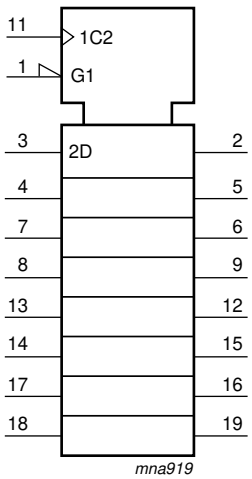


Fig 2. IEC logic symbol

5. Pinning information

5.1 Pinning

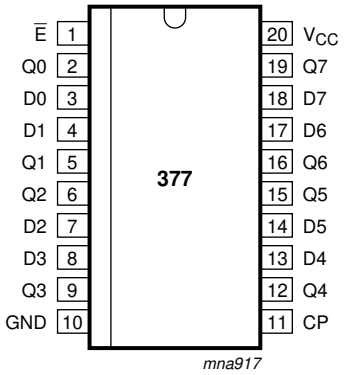


Fig 3. Pin configuration SO20 and (T)SSOP20

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
$\overline{E}$	1	data enable input (active LOW)
CP	11	clock input (LOW to HIGH; edge-triggered)
D[0:7]	3, 4, 7, 8, 13, 14, 17, 18	data input

Table 2. Pin description *?ontinued*

Symbol	Pin	Description
Q[0:7]	2, 5, 6, 9, 12, 15, 16, 19	flip-flop output
GND	10	ground (0 V)
V_{CC}	20	power supply

6. Functional description

Table 3. Function table[1]

Operating mode	Control		Input	Output
	CP	$\overline{E}$	Dn	Qn
Load 1	↑	l	h	H
Load 0	↑	l	l	L
Hold	↑	h	X	NC
Do nothing	X	H	X	NC

[1] H = HIGH voltage level
h = HIGH voltage level one set-up time prior to the LOW to HIGH CP transition
L = LOW voltage level
l = LOW voltage level one set-up time prior to the LOW to HIGH CP transition
↑ = LOW to HIGH CP transition
NC = no change
X = don't care

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CC}	supply voltage			−0.5	+6.5	V
V_I	input voltage		[1]	−0.5	+5.5	V
V_O	output voltage		[2]	−0.5	V_{CC} + 0.5	V
I_{IK}	input clamping current	V_I < 0 V		−50	-	mA
I_O	output current	V_O = 0 V to V_{CC}		-	±50	mA
I_{OK}	output clamping current	V_O > V_{CC} or V_O < 0 V		-	±50	mA
I_{CC}	supply current			-	100	mA
I_{GND}	ground current			−100	-	mA
T_{stg}	storage temperature			−65	+150	°C
P_{tot}	total power dissipation	T_{amb} = −40 °C to +125 °C	[3]	-	500	mW

[1] The minimum input voltage ratings may be exceeded if the input current ratings are observed.

[2] The output voltage ratings may be exceeded if the output current ratings are observed.

[3] For SO20 packages: above 70 °C derate linearly with 8 mW/K.
For (T)SSOP20 packages: above 60 °C derate linearly with 5.5 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage		1.65	-	3.6	V
		functional	1.2	-	-	V
V_I	input voltage		0	-	5.5	V
V_O	output voltage		0	-	V_{CC}	V
T_{amb}	ambient temperature	in free air	−40	-	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	V_{CC} = 1.65 V to 2.7 V	0	-	20	ns/V
		V_{CC} = 2.7 V to 3.6 V	0	-	10	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	−40 °C to +85 °C			−40 °C to +125 °C		Unit
			Min	Typ[1]	Max	Min	Max	
V_{IH}	HIGH-level input voltage	V_{CC} = 1.2 V	1.08	-	-	1.08	-	V
		V_{CC} = 1.65 V to 1.95 V	0.65 × V_{CC}	-	-	0.65 × V_{CC}	-	V
		V_{CC} = 2.3 V to 2.7 V	1.7	-	-	1.7	-	V
		V_{CC} = 2.7 V to 3.6 V	2.0	-	-	2.0	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 1.2 V	-	-	0.12	-	0.12	V
		V_{CC} = 1.65 V to 1.95 V	-	-	0.35 × V_{CC}	-	0.35 × V_{CC}	V
		V_{CC} = 2.3 V to 2.7 V	-	-	0.7	-	0.7	V
		V_{CC} = 2.7 V to 3.6 V	-	-	0.8	-	0.8	V
V_{OH}	HIGH-level output voltage	V_I = V_{IH} or V_{IL}						
		I_O = −100 μA; V_{CC} = 1.65 V to 3.6 V	V_{CC} − 0.2	-	-	V_{CC} − 0.3	-	V
		I_O = −4 mA; V_{CC} = 1.65 V	1.2	-	-	1.05	-	V
		I_O = −8 mA; V_{CC} = 2.3 V	1.8	-	-	1.65	-	V
		I_O = −12 mA; V_{CC} = 2.7 V	2.2	-	-	2.05	-	V
		I_O = −18 mA; V_{CC} = 3.0 V	2.4	-	-	2.25	-	V
		I_O = −24 mA; V_{CC} = 3.0 V	2.2	-	-	2.0	-	V
V_{OL}	LOW-level output voltage	V_I = V_{IH} or V_{IL}						
		I_O = 100 μA; V_{CC} = 1.65 V to 3.6 V	-	-	0.2	-	0.3	V
		I_O = 4 mA; V_{CC} = 1.65 V	-	-	0.45	-	0.65	V
		I_O = 8 mA; V_{CC} = 2.3 V	-	-	0.6	-	0.8	V
		I_O = 12 mA; V_{CC} = 2.7 V	-	-	0.4	-	0.6	V
		I_O = 24 mA; V_{CC} = 3.0 V	-	-	0.55	-	0.8	V
I_I	input leakage current	V_{CC} = 3.6 V; V_I = 5.5 V or GND	-	±0.1	±5	-	±20	μA

Table 6. Static characteristics *?ontinued*

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ[1]	Max	Min	Max	
I_{CC}	supply current	V_{CC} = 3.6 V; V_I = V_{CC} or GND; I_O = 0 A	-	0.1	10	-	40	µA
ΔI_{CC}	additional supply current	per input pin; V_{CC} = 2.7 V to 3.6 V; V_I = V_{CC} − 0.6 V; I_O = 0 A	-	5	500	-	5000	µA
C_I	input capacitance	V_{CC} = 0 V to 3.6 V; V_I = GND to V_{CC}	-	5.0	-	-	-	pF

[1] All typical values are measured at V_{CC} = 3.3 V (unless stated otherwise) and T_{amb} = 25 °C.

10. Dynamic characteristics

Table 7. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V). For test circuit see Figure 6.

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ[1]	Max	Min	Max	
t_{pd}	propagation delay	CP to Qn; see Figure 4 [2]						
		V_{CC}= 1.2 V	-	15	-	-	-	ns
		V_{CC}= 1.65 V to 1.95 V	2.5	7.4	14.5	2.5	15.5	ns
		V_{CC}= 2.3 V to 2.7 V	1.8	4.4	8.5	1.8	9.1	ns
		V_{CC} = 2.7 V	1.5	4.3	7.9	1.5	10.0	ns
		V_{CC} = 3.0 V to 3.6 V	1.5	4.0	7.6	1.5	9.5	ns
t_W	pulse width	clock HIGH or LOW; see Figure 4						
		V_{CC} = 1.65 V to 1.95 V	6.0	-	-	6.0	-	ns
		V_{CC} = 2.3 V to 2.7 V	5.0	-	-	5.0		ns
		V_{CC} = 2.7 V	5.0	1.6	-	5.0	-	ns
		V_{CC} = 3.0 V to 3.6 V	4.0	1.0	-	4.0	-	ns
t_{su}	set-up time	$\overline{E}$ to CP; see Figure 5						
		V_{CC} = 1.65 V to 1.95 V	5.5	-	-	5.5	-	ns
		V_{CC} = 2.3 V to 2.7 V	4.5	-	-	4.5		ns
		V_{CC} = 2.7 V	4.0	0.6	-	4.0	-	ns
		V_{CC} = 3.0 V to 3.6 V	3.0	0.2	-	3.0	-	ns
		Dn to CP; see Figure 5						
		V_{CC} = 1.65 V to 1.95 V	5.5	-	-	5.5	-	ns
		V_{CC} = 2.3 V to 2.7 V	4.5	-	-	4.5		ns
		V_{CC} = 2.7 V	3.0	1.0	-	3.0	-	ns
		V_{CC} = 3.0 V to 3.6 V	2.0	0.7	-	2.0	-	ns

Table 7. Dynamic characteristics *?ontinued*

Voltages are referenced to GND (ground = 0 V). For test circuit see Figure 6.

Symbol	Parameter	Conditions		–40 °C to +85 °C			–40 °C to +125 °C		Unit
				Min	Typ[1]	Max	Min	Max	
t_h	hold time	$\overline{E}$ to CP; see Figure 5							
		V_{CC} = 1.65 V to 1.95 V		1.5	-	-	1.5	-	ns
		V_{CC} = 2.3 V to 2.7 V		0.5	-	-	0.5		ns
		V_{CC} = 2.7 V		0.0	−1.0	-	0.0	-	ns
		V_{CC} = 3.0 V to 3.6 V		1.0	0	-	1.0	-	ns
		Dn to CP; see Figure 5							
		V_{CC} = 1.65 V to 1.95 V		1.5	-	-	1.5	-	ns
		V_{CC} = 2.3 V to 2.7 V		0.5	-	-	0.5		ns
		V_{CC} = 2.7 V		0.0	−1.1	-	0.0	-	ns
		V_{CC} = 3.0 V to 3.6 V		0.0	−1.0	-	0.0	-	ns
f_{max}	maximum frequency	see Figure 4							
		V_{CC} = 1.65 V to 1.95 V		80	-	-	64	-	MHz
		V_{CC} = 2.3 V to 2.7 V		100	-	-	80		MHz
		V_{CC} = 2.7 V		150	-	-	120	-	MHz
		V_{CC} = 3.0 V to 3.6 V		150	330	-	120	-	MHz
$t_{sk(o)}$	output skew time	V_{CC} = 3.0 V to 3.6 V	[3]	-	-	1.0	-	1.5	ns
C_{PD}	power dissipation capacitance	per flip-flop; V_I = GND to V_{CC}	[4]						
		V_{CC} = 1.65 V to 1.95 V		-	12.1	-	-	-	pF
		V_{CC} = 2.3 V to 2.7 V		-	15.8	-	-	-	pF
		V_{CC} = 3.0 V to 3.6 V		-	19.0	-	-	-	pF

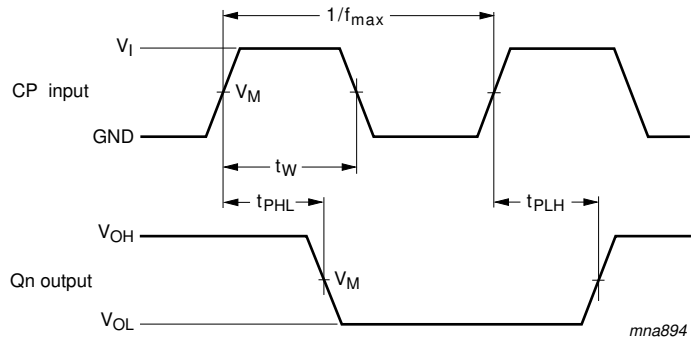
[1] Typical values are measured at T_{amb} = 25 °C and V_{CC} = 1.2 V, 1.8 V, 2.5 V, 2.7 V and 3.3 V respectively.

[2] t_{pd} is the same as t_{PLH} and t_{PHL}.

[3] Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.

[4] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:
f_i = input frequency in MHz; f_o = output frequency in MHz
C_L = output load capacitance in pF
V_{CC} = supply voltage in Volts
N = number of inputs switching
$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs

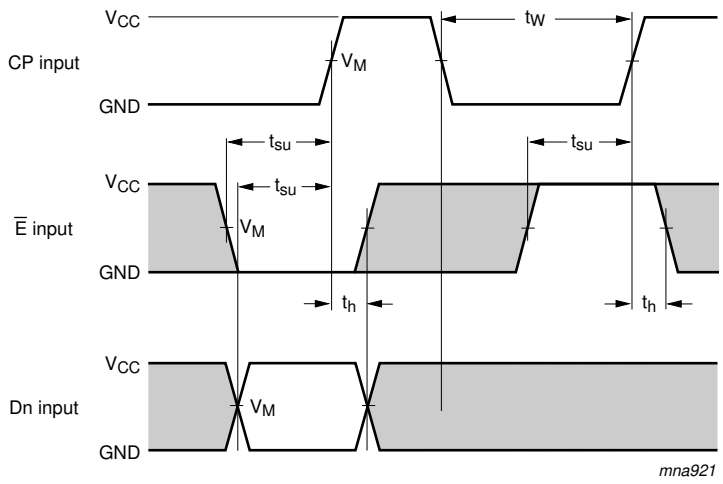
11. Waveforms



Measurement points are given in Table 8.

Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 4. Propagation delay clock (CP) to output (Qn), pulse width clock (CP), and maximum frequency



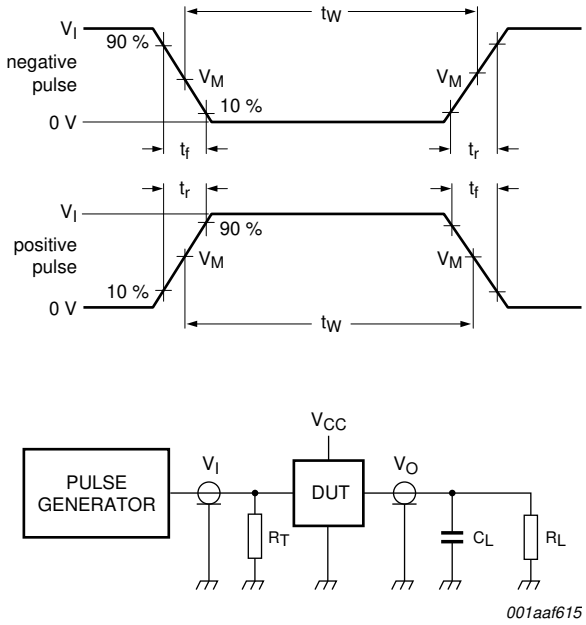
Measurement points are given in Table 8.

The shaded areas indicate when the input is permitted to change for predictable output performance.

Fig 5. Data set-up and hold times of data input (Dn) and enable input ($\overline{E}$) and pulse width of enable input ($\overline{E}$)

Table 8. Measurement points

Supply voltage	Input	Output
V_{CC}	V_M	V_M
1.2 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
1.65 V to 1.95V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
2.3 V to 2.7 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
2.7 V	1.5 V	1.5 V
3.0 V to 3.6 V	1.5 V	1.5 V



Test data is given in Table 9.

Definitions for test circuit:

R_L = Load resistance.

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

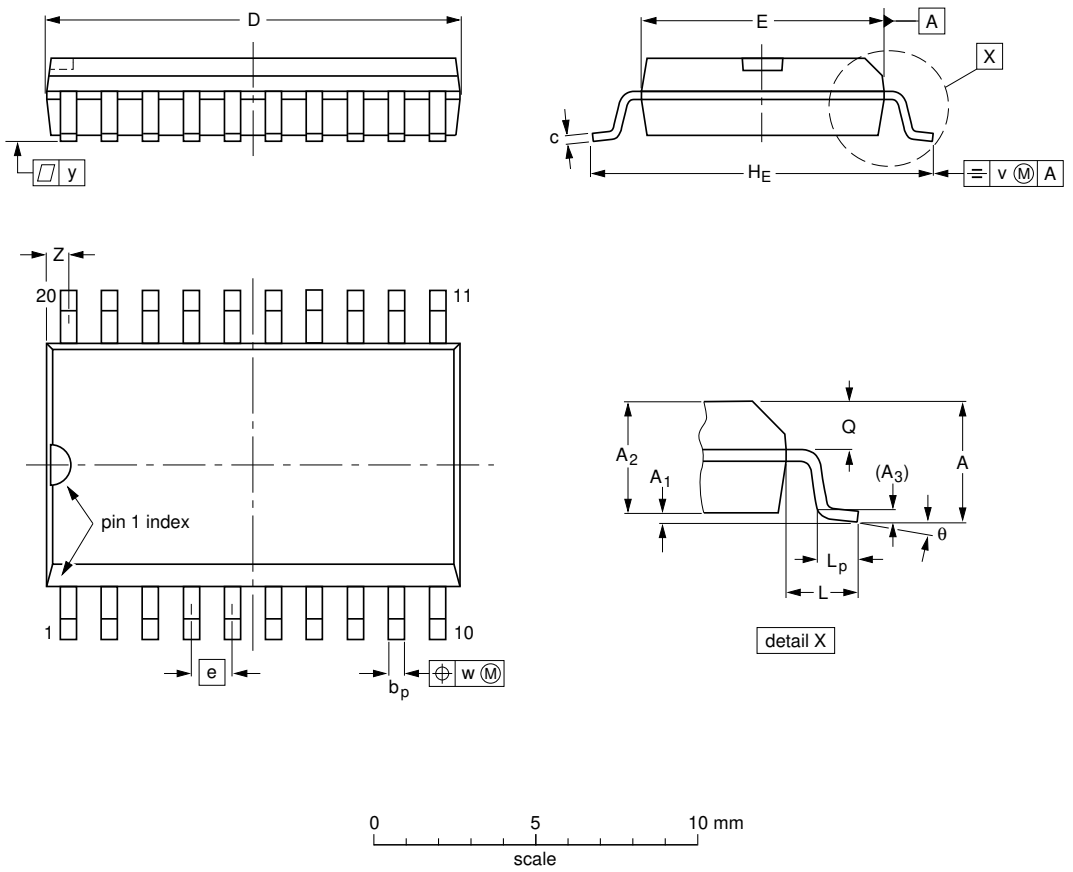
Fig 6. Test circuit for switching times

Table 9. Test data

Supply voltage	Input		Load	
	V_I	t_r, t_f	C_L	R_L
1.2 V	V_{CC}	≤ 2 ns	30 pF	1 kΩ
1.65 V to 1.95 V	V_{CC}	≤ 2 ns	30 pF	1 kΩ
2.3 V to 2.7 V	V_{CC}	≤ 2 ns	30 pF	500 Ω
2.7 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω
3.0 V to 3.6 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω

12. Package outline

SO20: plastic small outline package; 20 leads; body width 7.5 mm **SOT163-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	2.65	0.3 0.1	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.1	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.05	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

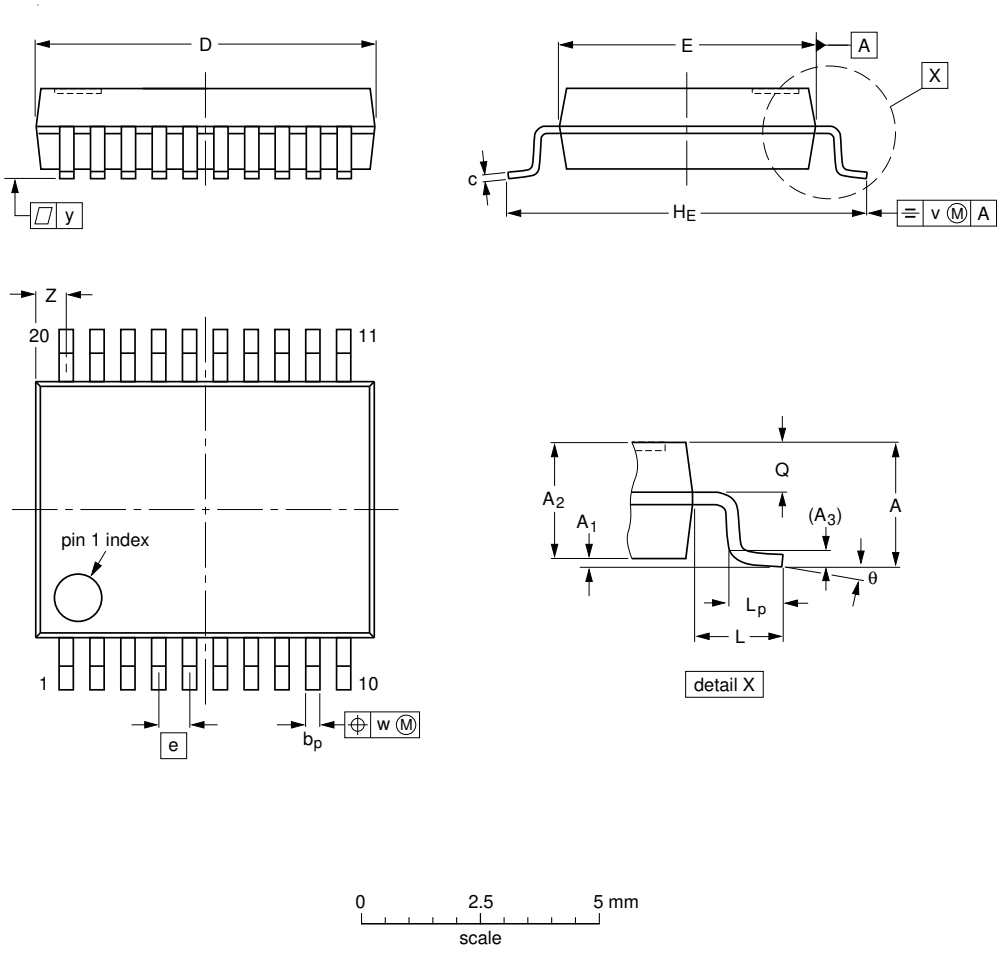
Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT163-1	075E04	MS-013				~~99-12-27~~ 03-02-19

Fig 7. Package outline SOT163-1 (SO20)

SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm **SOT339-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	2	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8^o 0^o

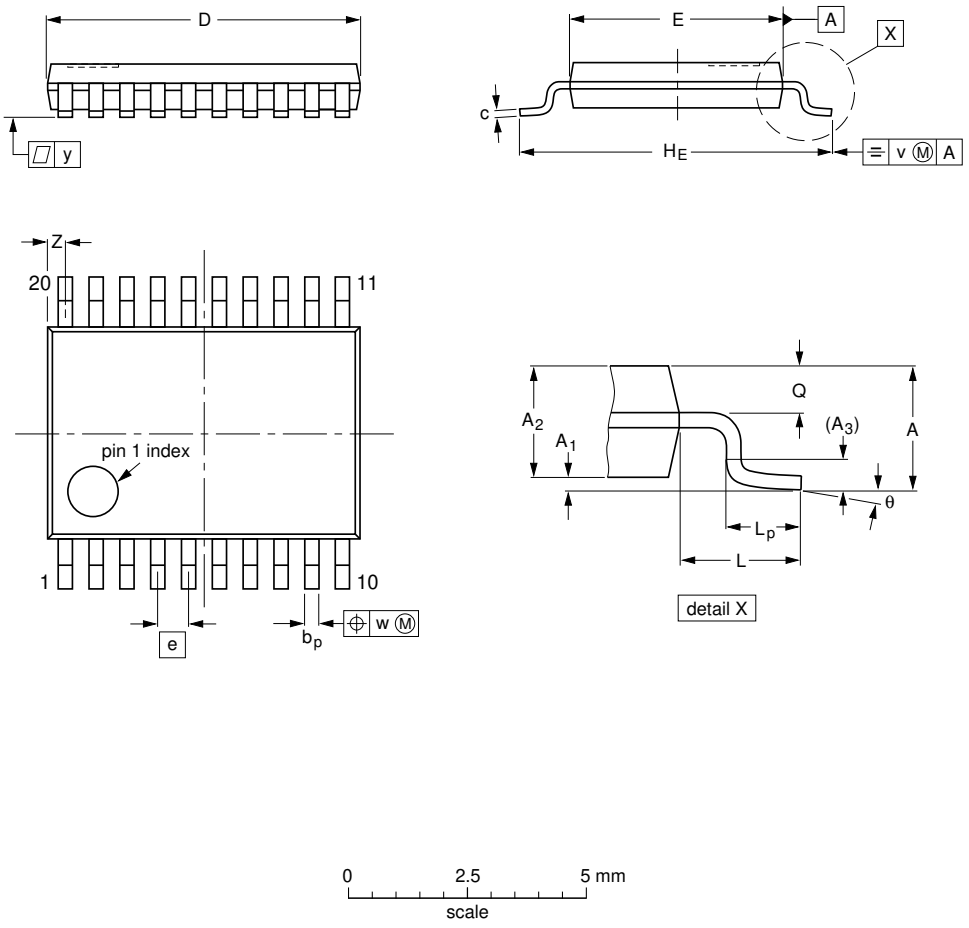
Note

1. Plastic or metal protrusions of 0.2 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT339-1		MO-150				~~99-12-27~~ 03-02-19

Fig 8. Package outline SOT339-1 (SSOP20)

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm **SOT360-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT360-1		MO-153				~~99-12-27~~ 03-02-19

Fig 9. Package outline SOT360-1 (TSSOP20)

13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC377 v.6	20121120	Product data sheet	-	74LVC377 v.5
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Table 4, Table 5, Table 6, Table 7, Table 8, and Table 9: values added for lower voltage ranges.			
74LVC377 v.5	20050221	Product specification	-	74LVC377 v.4
74LVC377 v.4	20040528	Product specification	-	74LVC377 v.3
74LVC377 v.3	20021023	Product specification	-	74LVC377 v.2
74LVC377 v.2	19980729	Product specification	-	74LVC377 v.1
74LVC377 v.1	19990606	Product specification	-	-

15. Legal information

15.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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For more information, please visit: **http://www.nxp.com**

For sales office addresses, please send an email to: **salesaddresses@nxp.com**

17. Contents

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Date of release: 20 November 2012
Document identifier: 74LVC377_6